## SEMiX 251D12Fs



# Bridge Rectifier Module (uncontrolled)

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Target Data

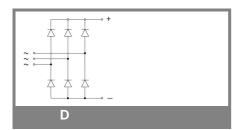
#### Features

- terminal height of 17mm
- chip solder on direct copper bonded Al<sub>2</sub>O<sub>3</sub> ceramic
- heat transfer through Al<sub>2</sub>O<sub>3</sub> ceramic isolated baseplate

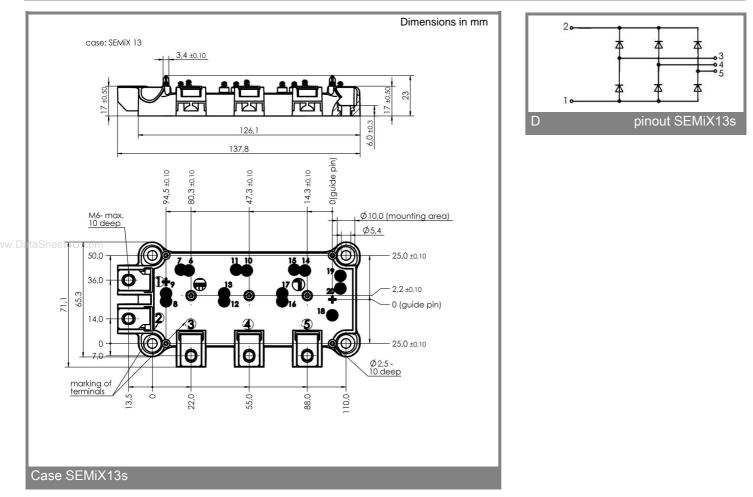
### **Typical Applications**

- Fast Input Bridge Rectifier for
- AC/DC motor control
- power supply
- high frequency applications

V <sub>RSM</sub>		V <sub>RRM</sub> , V <sub>DRM</sub>		I <sub>D</sub> = 250 A (full conduction)	
V		V	(T <sub>c</sub> = 85 °C)		
1200		1200		SEMiX 251D12Fs	
Symbol	Cor	ditions		Values	Units
$I_D = 85$				250	А
Б	$T_{\rm C} = 100 \ ^{\circ}{\rm C}$			215	
I <sub>FSM</sub>	<sub>SM</sub> T <sub>vj</sub> = 25 °C; 10 ms			1660	Α
	T <sub>vj</sub> = 150 °C; 10 ms			1330	A
i²t	$T_{vj} =$	25 °C; 8,3 10 ms		13700	A²s
	T <sub>vj</sub> = 150 °C; 8,3 10 ms			8800	A²s
V <sub>F</sub>	T <sub>vi</sub> =	25 °C; I <sub>F</sub> = 150 A		max. 2,5	V
V <sub>(TO)</sub>				max. 1,12	V
r <sub>T</sub>	T <sub>vi</sub> = 150 °C			max. 7,5	mΩ
I <sub>RD</sub>	$T_{vj}$ = 150 °C; $V_{DD}$ = $V_{DRM}$ ; $V_{RD}$ = $V_{RRM}$			max. 40	mA
					mA
R <sub>th(j-c)</sub>	per d	liode		0,26	K/W
(1)(-C)					K/W
R <sub>th(c-s)</sub>	per module			0,04	K/W
T <sub>vj</sub>				- 40 + 150	°C
T <sub>stg</sub>				- 40 + 125	°C
V <sub>isol</sub>	a. c. 50 Hz; r.m.s.; 1 s / 1 min.			4800 ( 4000 )	V
M <sub>s</sub>	(min.	/max.)		3/5	Nm
M <sub>t</sub>	(min./max.)			2,5/5	Nm
а				5 * 9,81	m/s²
m				300	g
Case	SEMiX 13s				



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